

JP 5-105739

AN 1993:562095 CAPLUS  
 DN 119:162095  
 TI Bisphenol-type **epoxy resin** compositions for sealing  
 semiconductor devices  
 IN Tauchi, Shigeaki; Tamai, Norya  
 PA Shinnittetsu Kagaku, Japan  
 SO Jpn. Kokai Tokkyo Koho, 7 pp.  
 CODEN: JKXXAF  
 DT Patent  
 LA Japanese  
 IC ICM C08G059-18  
 ICS C08G059-62; C08K003-36; C08L063-00; H01L023-29; H01L023-31  
 CC 38-3 (Plastics Fabrication and Uses)  
 Section cross-reference(s): 76

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 05105739	A2	19930427	JP 1991-296445	19911016
AB	Solder heat-resistant title compns. with low stress contain 100 parts <b>epoxy resins</b> contg. .gtoreq.30% biphenyl-type <b>epoxy resins</b> , 300-1000 parts silica filler, 1-30 parts <u>oils (R1)(SiR2R3O)nSiR4 (R1 = epoxy, amino, OH, OH-contg. group, SH; R2-4 =</u> <u>Me, Ph; n = no. to av. mol. wt. 1000-30,000), and 20-100 parts hardeners.</u> <u>Thus, a mixt. of YX 4000 100, tetraphenolethane 50, globular powd. silica</u> <u>500, crushed powd. silica 200, an epoxy-terminated silicone oil 5,</u> <u>.gamma.-glycidoxypropyltrimethoxysilane 4, Ph3P 1, carbon black 3, and a</u> <u>wax 3 parts was kneaded at 110.degree. for 4 min, crushed, molded onto an</u> <u>integrated circuit, and postcured at 85.degree. and 85% humidity for 72 h</u> <u>to give a test piece, which was impregnated with solder bath at</u> <u>260.degree. for 10 s to show no cracks.</u> semiconductor device sealant <b>epoxy resin</b> ; solder heat crack resistance sealant; biphenyl <b>epoxy resin</b> siloxane sealant; silica filler <b>epoxy resin</b> sealant Potting compositions (biphenyl-type <b>epoxy resins</b> contg. siloxanes, with solder heat resistance, for semiconductor devices) Heat-resistant materials (bisphenol-type <b>epoxy resin</b> -siloxanes, sealants, for semiconductor devices) Phenolic resins, uses RL: MOA (Modifier or additive use); USES (Uses) (crosslinking agents, for <b>epoxy resins</b> contg. functional group-terminated siloxanes, for sealants, for semiconductor devices) Crosslinking agents (for <b>epoxy resins</b> contg. functional group-terminated siloxanes, for sealants, for semiconductor devices) Siloxanes and Silicones, uses RL: USES (Uses) (epoxy, sealing compns., contg. silica fillers, with solder heat resistance, for semiconductor device) Siloxanes and Silicones, compounds RL: USES (Uses) (epoxy-terminated, reaction products with <b>epoxy</b> <b>resins</b> , for sealants, for semiconductor devices) <b>Epoxy resins</b> , uses RL: USES (Uses) (siloxane-, sealing compns., contg. silica fillers, with solder heat resistance, for semiconductor device)				

IT 7727-33-5

RL: MOA (Modifier or additive use); USES (Uses)

(crosslinking agents, for **epoxy resins** contg.  
functional group-terminated siloxanes, for sealants, for semiconductor  
devices)

IT 25639-41-2

RL: MOA (Modifier or additive use); USES (Uses)

(crosslinking agents, for **epoxy resins** contg.  
functional group-terminated siloxanes, for sealants, for semiconductor  
devices)

IT 60676-86-0, Fused silica

RL: USES (Uses)

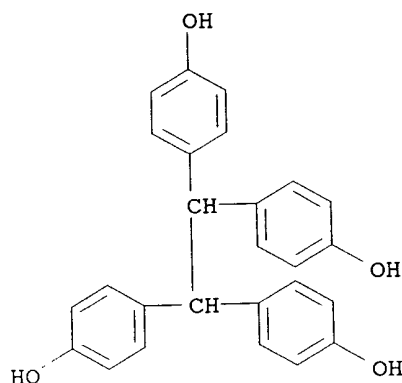
(powd., fillers, for **epoxy resin** sealing compns.  
contg. functional group-contg. siloxanes, for semiconductor devices)

IT 89118-70-7DP, YX 4000, reaction products with siloxanes

RL: PREP (Preparation)

(prepn. of, sealants, with solder heat resistance, for semiconductor  
devices)

RN 7727-33-5 REGISTRY  
 CN Phenol, 4,4',4'',4'''-(1,2-ethanediylidene)tetrakis- (9CI) (CA INDEX NAME)  
 OTHER CA INDEX NAMES:  
 CN Phenol, 4,4',4'',4'''-ethanediylidenetetra- (6CI)  
 OTHER NAMES:  
 CN 1,1,2,2-Tetrakis(4-hydroxyphenyl)ethane  
 CN 1,1,2,2-Tetrakis(p-hydroxyphenyl)ethane  
 CN TEP-DF  
 MF C26 H22 O4  
 CI COM  
 LC STN Files: BEILSTEIN\*, BIOSIS, CA, CAOLD, CAPLUS, CASREACT, CHEMCATS, CHEMLIST, IFICDB, IFIUDB, TOXLIT, USPATFULL  
 (\*File contains numerically searchable property data)  
 Other Sources: EINECS\*\*, NDSL\*\*, TSCA\*\*  
 (\*\*Enter CHEMLIST File for up-to-date regulatory information)



59 REFERENCES IN FILE CA (1967 TO DATE)  
 8 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA  
 59 REFERENCES IN FILE CAPLUS (1967 TO DATE)  
 1 REFERENCES IN FILE CAOLD (PRIOR TO 1967)